

B9 QAP B33

PATENTS ABSTRACTS OF JAPAN

Abstract 4A is related to

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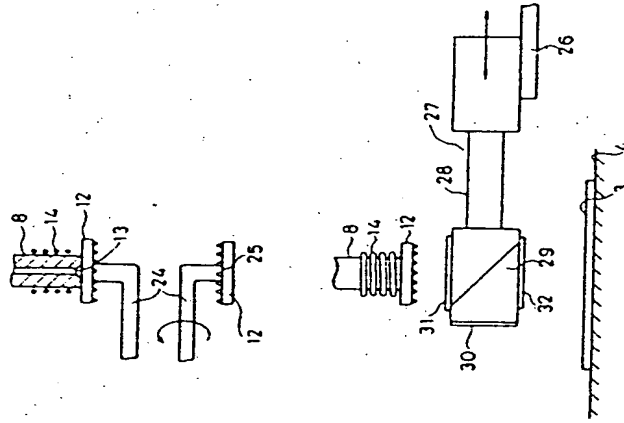
00: data card, 31: wiring substrate

(54) CHIP BONDING DEVICE

- (11) 2-226737 (A) (43) 10.9.1990 (19) JP
 (21) Appl. No. 64-45246 (22) 28.2.1989
 (71) TOSHIBA CORP (72) MINEAKI IIDA(2)
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PURPOSE: To make alignment and mount an electrode of a chip with high precision even in a fine pitch wiring by a method wherein the chip in face down state is fed from a chip feeding part to a bonding tool and then the relative position of a circuit board and the chip is detected by a two visional position detecting optical system.

CONSTITUTION: A chip 12 sucked at a suction part 25 is fed in the face down state to the rear side of a bonding tool 8. Since this bonding tool is provided with another vacuum suction part 13, the chip 12 sucked at the suction part 25 of an arm 24 is sucked at the suction part 13. When a circuit board 3 and the chip 12 are opposed at an interval, a two visional position detecting optical system 27 is actuated to detect the relative position of the board 3 and the chip 12. Then, a chip side shutter 31 and a board side shutter 32 alternately open and close so that a control part may take the picture images of the board 3 and the chip 12 to measure the slippage amount of both elements. Consequently, the shift correcting signals are inputted from the control part to a board loading stage and a bonding head 7 so as to perform the alignment and mounting process of the board 3 and the chip 12.



LEGENDE zu den Bibliographiedaten

- (54) Titel der Patentanmeldung (22) Anmeldetag in Japan
 (11) Nummer der JP-A2 Veröffentlichung (71) Anmelder (72) Erfinder
 (21) Aktenzeichen der JP-Anmeldung (52) Japanische Patentklassifikation
 (43) Veröffentlichungstag (51) Internationale Patentklassifikation

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